Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3064	(gold au) adj. bump	US-PGPUB; USPAT; EPO; JPO;	OR	ON	2004/12/11 15:51
			DERWENT; IBM_TDB			
L2	5027230	gold au	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2004/12/11 15:51
L3	668820	nickle nickel ni	US-PGPUB; USPAT; EPO; JPO; DERWENT;	OR	ON	2004/12/11 15:51
L4	1209554	copper cu	IBM_TDB US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 15:51
L5	635	2 sc/j 3 sc/j 4	US-PGPUB; USPAT; EPO; JPO; DERWENT;	OR	ON	2004/12/11 15:52
L6	7142	438/613-617.cc/s, 257/737,738.cc/s, 228/180.22	IBM_TDB US-PGPUB;	OR	ON	2004/12/11 15:53
10,12,1111			USPAT; EPO; JPO; DERWENT; IBM_TDB			
L7	46	5 and 6	US-PGPUB; USPAT; EPO; JPO;	OR	ON	2004/12/11 15:53
L8	762440	@ad>"20030320" @rlad>"20030320" @pt1d>"20030320"	DERWENT; IBM_TDB US-PGPUB;	OR	ON	2004/12/11 15:53
20	702770	<u> </u>	USPAT; EPO; JPO; DERWENT; IBM_TDB			2557/2777555
L9	45	7.not 8	US-PGPUB; USPAT; EPO; JPO;	OR	ON	2004/12/11 15:54
L10	1830	4 adj solder	DERWENT; IBM_TDB US-PGPUB;	OR	ON	2004/12/11 15:54
2,0	7000	4 auj souder	USPAT; EPO; JPO; DERWENT; IBM_TDB	Jon	0,1	2004/277 13.34
L11	152	10 and 6 not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT;	OR	ON	2004/12/11 15:54
L12	2	11 and 9	IBM_TDB US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:04
L13	87938	bump ,	US-PGPUB; USPAT; EPO; JPO;	OR	ON	2004/12/11 16:04
			DERWENT; IBM_TDB			
L14	18	13 with 5 not (11 6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:12
L15	1783	257/e23.021	US-PGPUB; USPAT; EPO; JPO;	OR	ON	2004/12/11 16:13
L16	953	257/e23.068	DERWENT; IBM_TDB US-PGPUB;	OR	ON -	2004/12/11 16:13
			USPAT; EPO; JPO; DERWENT; IBM_TDB	:		
L17	1529	257/e23.069	US-PGPUB; USPAT; EPO; JPO;	OR	ON	2004/12/11 16:13
L18	1830	257/a21 508	DERWENT; IBM_TDB US-PGPUB;	00	ON	2004/42/44 45:44
LIS	1830	257/e21.508	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 16:14

L19	3271	17 18	US-PGPUB; USPAT;	OR	ON	2004/12/11 16:14
			EPO; JPO; DERWENT;			
L20	8	19 and 5 not (6.7.9.14)	IBM_TDB US-PGPUB; USPAT;	OR	ON	2004/12/11 16:16
	111111111111111111111111111111111111111		EPO; JPO; DERWENT;			
L21	57	10 and 19 not (6 7 9 14 20)	US-PGPUB; USPAT;	OR	ON	2004/12/11 16:21
			EPO; JPO; DERWENT;			
L22	152	2 adj 1	IBM_TDB US-PGPUB; USPAT;	OR	ON	2004/12/11 16:21
			EPO; JPO; DERWENT; IBM_TDB			
L23	3	22 with 3 with 4	US-PGPUB; USPAT;	OR	ON	2004/12/11 16:35
		·	EPO; JPO; DERWENT; IBM_TDB			
L24		(12002/0056906T).URPN.	USPAT	OR	ON	2004/12/11 16:32
L25	77	1 with 3 with 4	US-PGPUB; USPAT; EPO; JPO;	OR	ON	2004/12/11 16:36
L26	55	25 not 6	DERWENT;   IBM_TDB   US-PGPUB;	OR	ON	2004/12/11 16:49
LZO		25,000	USPAT; EPO; JPO;		UN	2004/12/11:16:49
L27	3	*06056661*	DERWENT; IBM_TDB US-PGPUB:	OR	ON	2004/12/11 16:50
			USPAT; EPO; JPO;			2004/12/11 10:30
L28	2	*07240420*	DERWENT; IBM_TDB US-PGPUB:	OR	ON	2004/12/11 16:55
			USPAT; EPO; JPO; DERWENT;			
L29	1	1995-354177.NRAN.	IBM_TDB  DERWENT	OR	ON	2004/12/11 16:50
L30 L31	1 37416	2004-697794.NRAN. 2 with 3 with 4	DERWENT US-PGPUB:	OR OR	ON ON	2004/12/11 16:52 2004/12/11 16:56
	0,410		USPAT; EPO; JPO;			2004/12/11 10:30
L32	22492	4.with solder	DERWENT; IBM_TDB US-PGPUB;	OR	ON	2004/12/11 16:56
			USPAT; EPO; JPO; DERWENT;			
L33	3609	31 and 32	IBM_TDB US-PGPUB;	OR	ON	2004/12/11 16:56
			USPAT; EPO; JPO; DERWENT;			
L35	660	31 with bump	IBM_TDB US-PGPUB;	OR	ON	2004/12/11 16:58
			USPAT; EPO; JPO; DERWENT;			
L37	734	33 and (6 19)	IBM_TDB US-PGPUB;	OR	ON	2004/12/11 16:59
			USPAT; EPO; JPO; DERWENT;			
L38	688	31 and 32 and (6 19) not 8:	IBM_TDB US-PGPUB;	OR	ON	2004/12/11 16:59
			USPAT; EPO; JPO; DERWENT;			
L39	172	38 not (6 7 9 14 20 21)	IBM_TDB US-PGPUB;	OR	ON	2004/12/11 17:11
			USPAT; EPO; JPO; DERWENT;			
L41	169	438/614.ccls, and 31	IBM_TDB US-PGPUB; USPAT;	OR	ON	2004/12/11 17:12
			EPO; JPO; DERWENT;			
L42	157	41 not 8	IBM_TDB US-PGPUB; USPAT;	OR	ON	2004/12/11 17:12
			EPO; JPO; DERWENT;			
<u></u>	ab Histo	rv 12/11/04 10:16:38 PM Page 2	IBM_TDB	Щ		

L43	7	(US-20030234276-\$ or US-20030155638-\$ or US-20020056906-\$ or US-20020061641-\$).did. or (US-4078980-\$ or US-6809020-\$ or US-4042954-\$).did.	US-PGPUB; USPAT	OR	ON	2004/12/11 18:09
L44	7	semiconductori adj flipi adj chipi adj wafer	US-PGPUB; USPAT; EPO; JPO;	OR	ON	2004/12/11 18:59
			DERWENT; IBM_TDB			
L45	761	semiconductor! adj chip! adj wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR -	ON	2004/12/11 19:04
L46	3326	(topl:upperl) edj.wafer.	US-PGPUB; USPAT; EPO; JPO; DERWENT;	OR	ON	2004/12/11 19:04
L48	2016916	"438"/\$.ccls. "257"/\$.ccls. semiconductor integrated adj circuit ic 228/180.22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:05
L49	350041	dice\$ dicing scrib\$ saw\$	US-PGPUB; USPAT; EPO; JPO; DERWENT;	OR	ON	2004/12/11 19:06
L50	49	46 with 49	IBM_TDB US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:06
L52	47	50'not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:08
L53	762	46 and 49	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:09
L54	94	flip! adj chip and 53	US-PGPUB; USPAT; EPO; JPO; DERWENT;	OR	ON	2004/12/11 19:09
L55	84	54 not 8	IBM_TDB US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:10
L56	2	(*5,952,725*).PN	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 19:13
L57	755	438/113.ccls. not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT;	OR	ON	2004/12/11 19:13
L58	150	flipl adj.chip.and 57	US-PGPUB; US-PGPUB; USPAT; EPO; JPO; DERWENT;	OR	ON	2004/12/11 19:21
L59	4788	cu adj sn	IBM_TDB US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 19:22
L60	4	5.with:59	US-PGPUB; USPAT; EPO; JPO; DERWENT;	OR	ON	2004/12/11 20:30
L61	6178	4 with (tin sn) with wt\$4	US-PGPUB; US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	-OR	ON -	-2004/12/11 20:32 <sup>-</sup>
L62	11	438/614 and 61 not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT;	OR	ON	2004/12/11: 20:33
L63	11	(US-20030234276-\$ or US-20030155638-\$ or US-20020056906-\$ or US-20020061641-\$).did. or (US-4078980-\$ or US-6809020-\$ or US-4042954-\$ or US-6762506-\$ or US-6638847-\$ or US-6334570-\$ or US-6325279-\$).did.	IBM_TDB US-PGPUB; USPAT	OR	ON	2004/12/11 21:29

L64	12		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 21:30
£65		64 not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR		2004/12/11:21:32
L66	164	electroplat\$ with electroless\$ with bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/11 21:33
L67	152	:66 not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR		2004/12/11 21:33



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2 entries found for **solder**. To select an entry, click on it.

solder[1,noun] solder[2,verb]



Main Entry: 1sol·der 剩

Pronunciation: 'sā-d&r, 'so-, British also 'sāl-d&r, 'sol-

Function: noun

Etymology: Middle English soudure, from Middle French, from souder to solder, from Latin solidare to make solid, from solidus solid

1: a metal or metallic alloy used when melted to join metallic surfaces; especially: an alloy of lead and tin so used

2: something that unites

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